

ON Semiconductor®

FDP8030L/FDB8030L

N-Channel Logic Level PowerTrench® MOSFET

General Description

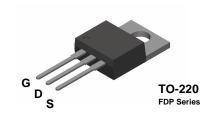
This N-Channel Logic level MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers.

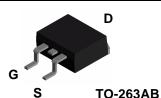
These MOSFETS feature faster switching and lower gate charge than other MOSFETS with comparable $R_{\text{DS(on)}}$ specifications.

The result is a MOSFET that is easy and safer to drive (even at very high frequencies), and DC/DC power supply designs with higher overall efficiency.

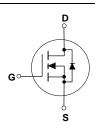
Features

- 80 A, 30 V. $R_{DS(ON)} = 0.0035 \; \Omega \; @ \; V_{GS} = 10 \; V$ $R_{DS(ON)} = 0.0045 \; \Omega \; @ \; V_{GS} = 4.5 \; V$
- Critical DC electrical parameters specified at elevated temperature
- Rugged internal source-drain diode can eliminate the need for an external Zener diode transient suppressor
- High performance trench technology for extremely low $R_{\mbox{\scriptsize DS}(\mbox{\scriptsize ON})}$
- 175°C maximum junction temperature rating





FDB Series



Absolute Maximum Ratings TA=25°C unless otherwise noted

| Symbol | Parameter | | Ratings | Units |
|-------------------|---|----------|-------------|-------|
| V_{DSS} | Drain-Source Voltage | | 30 | V |
| V_{GSS} | Gate-Source Voltage | | ±20 | V |
| I _D | Drain Current - Continuous | (Note 1) | 80 | А |
| | – Pulsed | (Note 1) | 300 | |
| P _D | Total Power Dissipation @ $T_C = 25^{\circ}C$ Derate above 25°C | | 187 | W |
| | | | 1.25 | W°C |
| T_J , T_{STG} | Operating and Storage Junction Temperature Range | | -65 to +175 | °C |
| T _L | Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds | | 275 | °C |

Thermal Characteristics

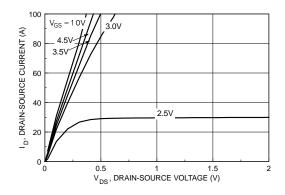
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case | 0.8 | °C/W | | | |
|-----------------|---|------|------|--|--|--|
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | 62.5 | °C/W | | | |

| Symbol | Parameter | Test Conditions | Min | Тур | Max | Units |
|--|--|---|-----|------------|------------|-------|
| Drain-Sc | ource Avalanche Ratings (Note | 1) | | | | |
| W _{DSS} | Single Pulse Drain-Source Avalanche Energy | $V_{DD} = 20 \text{ V}, \qquad I_{D} = 80 \text{ A}$ | | | 1500 | mJ |
| I _{AR} | Maximum Drain-Source Avalanche Current | | | | 80 | Α |
| Off Char | acteristics | | | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$ | 30 | | | V |
| ΔBV _{DSS} ΔT _J | Breakdown Voltage Temperature Coefficient | $I_D = 250 \mu\text{A}$, Referenced to 25°C | | 23 | | mV/°C |
| I _{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = 24 \text{ V}, \qquad V_{GS} = 0 \text{ V}$ | | | 10 | μΑ |
| I _{GSSF} | Gate-Body Leakage, Forward | $V_{GS} = 20 \text{ V}, \qquad V_{DS} = 0 \text{ V}$ | | | 100 | nA |
| I _{GSSR} | Gate-Body Leakage, Reverse | $V_{GS} = -20 \text{ V}$ $V_{DS} = 0 \text{ V}$ | | | -100 | nA |
| On Char | acteristics (Note 2) | | | | | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$ | 1 | 1.5 | 2 | V |
| $\frac{\Delta V_{GS(th)}}{\Delta T_J}$ | Gate Threshold Voltage Temperature Coefficient | $I_D = 250 \mu\text{A}$, Referenced to 25°C | | - 5 | | mV/°C |
| R _{DS(on)} | Static Drain–Source On–Resistance | $V_{GS} = 10 \text{ V}, \qquad I_{D} = 80 \text{ A} $ $T_{J} = 125 ^{\circ}\text{C}$ | | 3.1 4.0 | 3.5 5.6 | mΩ |
| | | $V_{GS} = 4.5 \text{ V}, \qquad I_{D} = 70 \text{ A}$ | | 3.6 | 4.5 | |
| $I_{D(on)}$ | On–State Drain Current | $V_{GS} = 10 \text{ V}, \qquad V_{DS} = 10 \text{ V}$ | 60 | | | Α |
| g _{FS} | Forward Transconductance | $V_{DS} = 10 \text{ V}, \qquad I_{D} = 80 \text{ A}$ | | 170 | | S |
| Dynamic | : Characteristics | | | | | |
| Ciss | Input Capacitance | $V_{DS} = 15 \text{ V}, \qquad V_{GS} = 0 \text{ V},$ | | 10500 | | pF |
| Coss | Output Capacitance | f = 1.0 MHz | | 2700 | | pF |
| C _{rss} | Reverse Transfer Capacitance | | | 1650 | | pF |
| Switchin | g Characteristics (Note 2) | | | | | |
| t _{D(on)} | Turn-On Delay Time | $V_{DD} = 15 \text{ V}, \qquad I_{D} = 50 \text{ A},$ | | 20 | 35 | ns |
| t _r | Turn-On Rise Time | $V_{GS} = 4.5 \text{ V}, \qquad R_{GEN} = 10 \Omega$ | | 185 | 225 | ns |
| t _{D (off)} | Turn-Off Delay Time | $R_{GS} = 10 \Omega$ | | 160 | 200 | ns |
| t _f | Turn-Off Fall Time | | | 200 | 240 | ns |
| Q _g | Total Gate Charge | V _{DS} = 15 V, I _D = 80 A, V _{GS} = 5 V | | 120 | 170 | nC |
| Q_{gs} | Gate-Source Charge | | | 27 | | nC |
| Q_{gd} | Gate-Drain Charge | | | 48 | | nC |
| Drain-S | ource Diode Characteristics | and Maximum Ratings | | | | |
| Is | Maximum Continuous Drain-Source | Diode Forward Current (Note 1) | | | 80 | Α |
| I _{SM} | Maximum Pulsed Drain-Source Diode Forward Current (Note 1) | | | | 300 | Α |
| V_{SD} | Drain-Source Diode Forward Voltage | $V_{GS} = 0 \text{ V}, I_S = 80 \text{ A} \text{ (Note 1)}$ | | 1 | 1.3 | V |

Notes:

^{1.} Pulse Test: Pulse Width < 300µs, Duty Cycle < 2.0%

Typical Characteristics



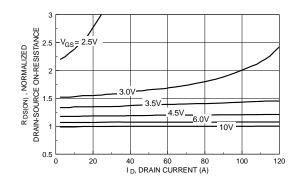
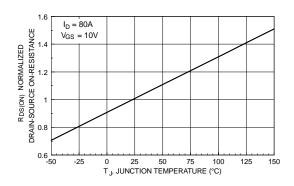


Figure 1. On-Region Characteristics.

Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.



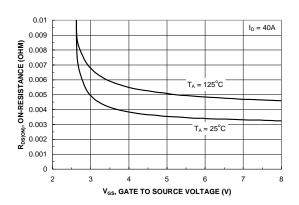
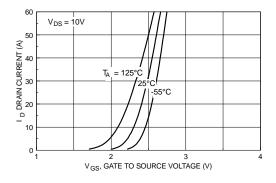


Figure 3. On-Resistance Variation with Temperature.

Figure 4. On-Resistance Variation with Gate-to-Source Voltage.



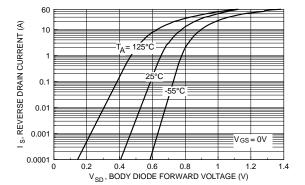
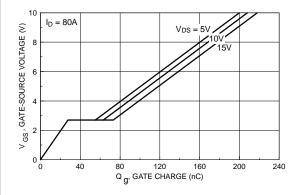


Figure 5. Transfer Characteristics.

Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics

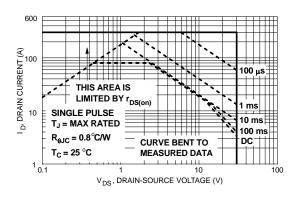


10000 Ciss
5000 Coss
1000 V_{GS} = 0V Crss
V_{DS}, DRAIN TO SOURCE VOLTAGE (V)

18000

Figure 7. Gate Charge Characteristics.





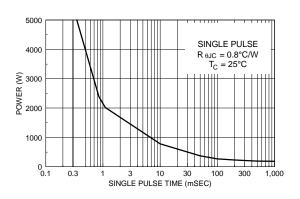


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

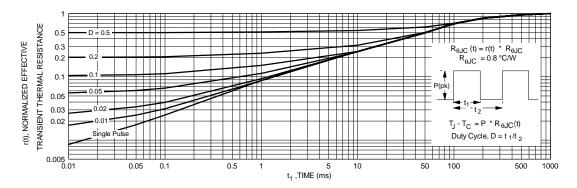


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c.

Transient thermal response will change depending on the circuit board design.

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